

Title (en)

PHOTODIODE ARRAY AND METHOD FOR ESTABLISHING A LINK BETWEEN A FIRST SEMICONDUCTOR ELEMENT AND A SECOND SEMICONDUCTOR ELEMENT

Title (de)

PHOTODIODENANORDNUNG UND VERFAHREN ZUR HERSTELLUNG EINER VERBINDUNG ZWISCHEN EINEM ERSTEN HALBLEITERBAUELEMENT UND EINEM ZWEITEN HALBLEITERBAUELEMENT

Title (fr)

ENSEMBLE PHOTODIODE ET PROCEDE POUR LA PRODUCTION D'UNE LIAISON ENTRE UN PREMIER COMPOSANT SEMI-CONDUCTEUR ET UN DEUXIEME COMPOSANT SEMI-CONDUCTEUR

Publication

EP 1464084 A1 20041006 (DE)

Application

EP 02704576 A 20020109

Priority

DE 0200067 W 20020109

Abstract (en)

[origin: WO03058720A1] The invention relates to a photodiode array comprising a photodiode and a submount, via which the photodiode is contacted, said photodiode (1) and said submount (2) being interlinked by eutectic bonding. The invention further relates to a method for establishing a link between a first semiconductor element and a second semiconductor element which have different outer contours, the two elements being interlinked by eutectic bonding when already being present as a wafer composite. The two interlinked wafers are subdivided one by one and independently of each other in accordance with the desired outer contour.

IPC 1-7

H01L 25/16; **H01L 25/04**; **H01S 5/022**

IPC 8 full level

H01L 31/02 (2006.01); **H01L 31/101** (2006.01); **H01L 31/18** (2006.01); **H01S 5/022** (2006.01); **H01L 27/146** (2006.01)

CPC (source: EP US)

H01L 31/02005 (2013.01 - EP US); **H01L 31/02019** (2013.01 - EP US); **H01L 31/101** (2013.01 - EP US); **H01L 31/18** (2013.01 - EP US); **H01S 5/02325** (2021.01 - EP US); **H01L 27/14643** (2013.01 - EP US); **H01L 2224/48091** (2013.01 - EP US); **H01S 5/0683** (2013.01 - EP US); **H01S 5/423** (2013.01 - EP US)

Citation (search report)

See references of WO 03058720A1

Designated contracting state (EPC)

AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE TR

DOCDB simple family (publication)

WO 03058720 A1 20030717; EP 1464084 A1 20041006; US 2005110025 A1 20050526; US 7476906 B2 20090113

DOCDB simple family (application)

DE 0200067 W 20020109; EP 02704576 A 20020109; US 50120905 A 20050106